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/!\ REMINDERS

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- Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.
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Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required.

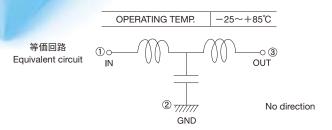
In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

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積層チップEMI除去フィルタ MULTILAYER EMI SUPPRESSION FILTER



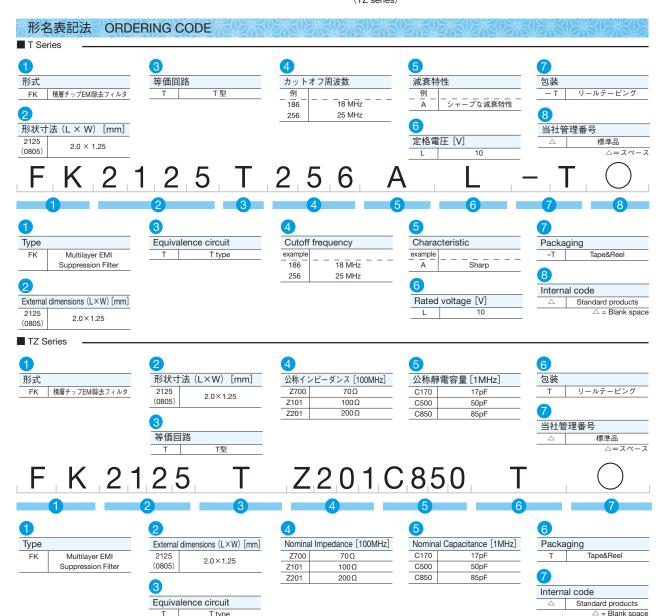


特長 FEATURES

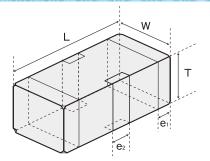
- ・積層コンデンサ、積層インダクタを一体化した2×1.25mmサイズのEMI フィルタです
- ・急峻な減衰特性の Tシリーズ と ディジタル信号の波形品位維持に効果 的な TZシリーズ をラインナップ
- ・積層コンデンサ等と同一形状で、自動機による高速実装に最適です
- 2×1.25mm size EMI filter unifying multilayer capacitor and inductor T series with rapid attenuation characteristics and TZ series with effective maintaining of waveform quality of digital signal are lined up.
- Same shape as multilayer capacitor which is suitable for high speed mounting by automatic machine.

用途 APPLICATIONS

- ・DVD、DSC、PDP等の映像信号に於けるノイズ対策(Tシリーズ)
- ・パソコン、情報機器等、ディジタル信号処理回路でのノイズ対策と波形 品位維持(TZシリーズ)
- Noise countermeasure in visual signal such as DVD, DSC, PDP, etc. (T series)
- Noise countermeasure and maintaining waveform quality in digital signal processing circuit in personal computer, communication equipment, etc. (TZ series)



外形寸法 EXTERNAL DIMENSIONS

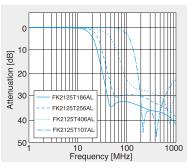


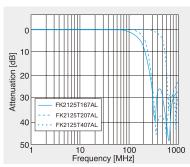
L	W	Т	e¹	e ²
2.0±0.2	1.25±0.2	1.0±0.2	0.3±0.2	0.4±0.2
(0.079±0.008)	(0.049±0.008)	(0.039±0.008)	(0.012±0.008)	(0.016±0.008)

Unit: mm (inch)

特性図 ELECTRICAL CHARACTERISTICS

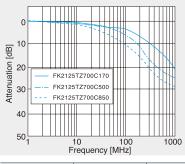
●Tシリーズ

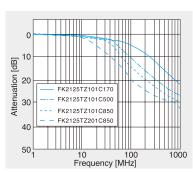




形 名 Ordering code	EHS (Environmental Hazardous Substances)	カットオフ周波数 Cut-Off Frequency	挿入損失 insertion-loss [1MHz]	[50MHz]	[100MHz]		減衰量 tenuatio		[600MHz]		resistance	定格電圧 Rated voltage	Rated	絶縁抵抗 Insulation resistance
FK2125T186AL	RoHS	18MHz±3.6MHz		≧20dB	≧20dB	_	_	≧20dB	_	_				
FK2125T256AL	RoHS	25MHz±5MHz		≧15dB	≧20dB	-	-	≧20dB	-	-	2Ω			
FK2125T406AL	RoHS	40MHz±10MHz		_	≧15dB	≧20dB	_	≧20dB	_	_				
FK2125T107AL	RoHS	100MHz±20MHz	≦1.0dB	-	_	≧20dB	_	≧20dB	_	_	3Ω	10V DC	100mA DC	≧30MΩ
FK2125T167AL	RoHS	160MHz±30MHz		-	-	_	≧20dB	≧20dB	ı	ı				
FK2125T207AL	RoHS	200MHz±40MHz		_	_	-	≧20dB	≧20dB	_	-	2Ω			
FK2125T407AL	RoHS	400MHz±80MHz		_	_	_	_	_	≧20dB	≧20dB				

●TZシリーズ





形 名 Ordering code	EHS (Environmental Hazardous Substances)	インピーダンス (端子1-3) impedance [100MHz]	静電容量 (端子1-2) capacitance [1MHz]	直流抵抗 DC resis- tance max.	定格電圧 Rated volt- age	定格電流 Rated cur- rent	絶縁抵抗 Insulation resistance
FK2125TZ700C170	RoHS	$70\Omega\pm30\%$	17pF±20%				
FK2125TZ700C500	RoHS	$70\Omega\pm30\%$	50pF±20%				
FK2125TZ700C850	RoHS	$70\Omega\pm30\%$	85pF±20%				
FK2125TZ101C170	RoHS	$100\Omega\pm30\%$	17pF±20%	2Ω	10V DC	100mA DC	≧30MΩ
FK2125TZ101C500	RoHS	$100\Omega\pm30\%$	50pF±20%				
FK2125TZ101C850	RoHS	$100\Omega\pm30\%$	85pF±20%				
FK2125TZ201C850	RoHS	$200\Omega\pm30\%$	85pF±20%				

▼ P.16

アイテム一覧 Part Numbers

Electrical Characteristics

Packaging P.444

梱包

信頼性 Reliability Data P.446 使用上の注意 Precautions

Selection Guide



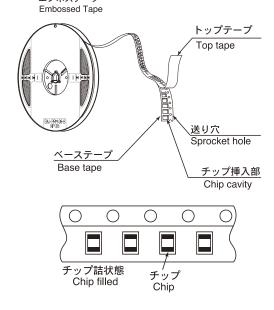
P.443

①最小受注単位数 Minimum Quantity

テーピング梱包

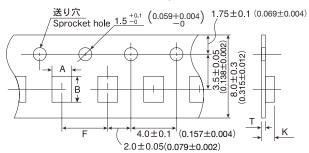
Type	製品厚み	標準数量 Standard quantity[pcs]
туре	Thickness [mm]	エンボステープ Embossed tape
FK 2125 (0805)	1.0	
FK 2125 (0805)	(0.039)	3000

②テーピング材質 Tape material エンボステープ



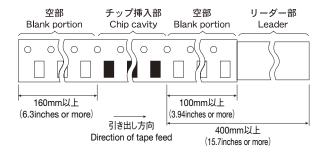
③テーピング寸法 Taping dimensions

エンボステープ (8mm幅) Embossed tape (0.031inches wide)

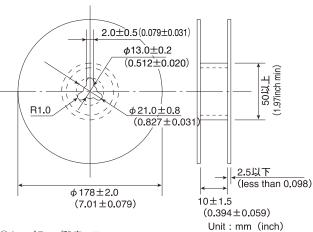


形式	チップ	挿入部	挿入ピッチ	テープ厚み			
Type	Chip	cavity	Insertion pitch	Tape thickness			
турс	А	В	F	K	Т		
	1.5±0.2	2.3±0.2	4.0±0.1	2.0	0.3		
FK 2125				max.	max.		
(0805)	(0.059±0.008)	(0.091±0.008)	(0.157±0.004)	(0.079)	(0.012)		
				max.	max.		
	Unit: mm (inch)						

④リーダー部/空部 Leader and Blank portion

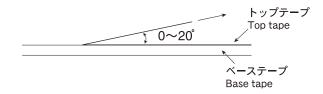


⑤リール寸法 Reel size



⑥トップテープ強度 Top tape strength

トップテープのはがし力は下図矢印方向にて0.1~0.7Nとなります。 The top tape requires a peel;-off force of $0.1 \sim 0.7 N$ in the direction of the arrow as illustrated below.



MULTILAYER EMI SUPPRESSION FILTER

Item	Specified	Test Methods and Remarks			
1. Operating Temperature Range	−25 to +85°C				
2. Storage Temperature Range	−25 to +85°C				
3. Rated Voltage	10V DC				
4. Rated Current	100mA DC				
5. Cutoff frequency (T Series)	18MHz±3.6MHz 25MHz±5MHz 40MHz±10MHz 100MHz±20MHz 160MHz±30MHz 200MHz±40MHz 400MHz±80MHz	Measuring equipment : HP8753D (or its equivalent) Measuring source : 0dBm Input-Outputimpedance : 50Ω			
6. Impedance(TZ Series)	70Ω±30% 100Ω±30% 200Ω±30%	Measuring frequency: 100MHz Measuring equipment: HP4291A (or its equivalent) Measuring jig: HP16192A Measuring source: -20dBm			
7. Capacitance(TZ Series)	17pF±20% 50pF±20% 85pF±20%	Measuring equipment : HP4194A (or its equivalent) Measuring voltage : 0.5V Measuring frequency : 1MHz Capacitance measurement between Terminals 1 and 2.			
8. DC Resistance	2Ω max. 3Ω max. (FK2125T107AL)	Conduct measurement between Terminals 1 and 3.			
9. Insulation Resistance	30MΩ min.	Conduct measurement between Terminals 1 and 2. Applied voltage: 10VDC			
10. Resistance to Flexure of Substrate	No mechanical damage.	Warp: 2mm Testing board: glass epoxy-resin substrate Thickness: 0.8mm Board R-230 Warp Warp (Unit: mm)			
11. Solderability	At least 75% of terminal electrode is covered by new solder.	Solder temperature: 230±5°C Duration: 4±1 sec. Preheating temperature: 150 to 180°C Preheating time: 2 to 3 min. Flux: Immersion into methanol solution with colophony for 3 to 5 sec			
12. Resistance to Soldering	No significant abnormality in appearance. Circuit diagram	Solder temperature: 260±5°C Duration: 10±0.5 sec. Preheating temperature: 150 to 180°C Preheating time: 2 to 3 min Flux: Immersion into methanol solution with colophony for 3 to 5 sec			
13. Thermal Shock	No mechanical damage. Insulation resistance (between 1 and 2) : $20M\Omega$ min. DC resistance (between 1 and 3) : 2Ω max. 3Ω max. (FK2125T107AL)	Conditions for 1 cycle Step1: Minimum operating temperature $+0/-3^{\circ}$ C 30 ± 3 min Step2: Room temperature 2 to 3 min Step3: Maximum operating temperature $+0/-3^{\circ}$ C 30 ± 3 min Step4: Room temperature 2 to 3 min Number of cycles: 5 Recovery: 2 to 3 hrs of recovery under the standard condition after the			
14. Damp Heatfsteady stateg	No mechanical damage. Insulation resistance (between 1 and 2): $20 \text{M}\Omega$ min. DC resistance (between 1 and 3): 2Ω max. 3Ω max. (FK2125T107AL)	Temperature: 40±2°C Humidity: 90 to 95%RH Duration: 500±12 hrs Recovery: 2 to 3 hrs of recovery under the standard condition after t removal from test chamber.			
15. Loading under Damp Heat	No mechanical damage. Insulation resistance (between 1 and 2): $20M\Omega$ min. DC resistance (between 1 and 3): 2Ω max. 3Ω max. (FK2125T107AL)	Temperature: 40±2°C Humidity: 90 to 95%RH Applied voltage: Rated voltage(between 1 and 2) Applied current: Rated current(between 1 and 3) Duration: 500±12 hrs Recovery: 2 to 3 hrs of recovery under the standard condition after to removal from test chamber.			
16. Loading at High Temperature	No mechanical damage. Insulation resistance (between 1 and 2): $20M\Omega$ min. DC resistance (between 1 and 3): 2Ω max. 3Ω max. (FK2125T107AL)	Temperature: 85±2°C Applied voltage: Rated voltage(between 1 and 2) Applied current: Rated current(between 1 and 3) Duration: 500±12 hrs Recovery: 2 to 3 hrs of recovery under the standard condition after t removal from test chamber.			

Note on standard condition : "standard condition" referred to herein is defined as follows : 5 to 35°C of temperature, 45 to 85% relative humidity and 86 to 106kPa of air pressure.

When there are questions concerning measurement results :

In order to provide correlation data, the test shall be conducted under condition of 20 $\pm 2^{\circ}\! C$ of temperature, 60 to 70% relative humidity and 86 to 106kPa of air pressure.

Unless otherwise specified, all the tests are conducted under the "standard condition."

*Circuit diagram

